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MAY 11 2007

Docket No. 740756-2710
Application No. 10/771,277
Page 8

REMARKS

The Office Action of January 11, 2007 was received and reviewed. The Examiner is thanked for reviewing this application. Reconsideration and withdrawal of the currently pending rejections are requested for the reasons advanced in detail below.

Filed concurrently herewith is a *Request for a One-Month Extension of Time* which extends the shortened statutory period of response to May 11, 2007. Accordingly, Applicant respectfully submits that this response is being timely filed.

Claims 1-7, 10-21 and 23-28 are pending in the instant application, of which claims 1-6, 10, 11, 14 and 15 are independent. By this Amendment, claims 1-6, 10 and 11 have been amended and claims 12, 13, 25 and 26 have been canceled without prejudice or disclaimer.

Referring now to the detailed Office Action, claims 1, 3, 4, 6, 7, 10-13, 16, 18, 19, 21 and 23-26 stand rejected under 35 U.S.C. §102(e) as being anticipated by Yamazaki et al. (U.S. Pat. Pub. 2005/0011752 – hereafter Yamazaki). Further, claims 1-7, 14, 15, 17-21, 27 and 28 stand rejected under 35 U.S.C. §103(a) as being unpatentable over Ishikawa (U.S. Patent No. 5,429,994 – hereafter Ishikawa) in view of Ogawa (U.S. Patent No. 6,871,943 – hereafter Ogawa) and Koinuma et al. (U.S. Patent No. 5,549,780 – hereafter Koinuma). Still further, claims 10, 11, 23 and 24 stand rejected under 35 U.S.C. §103(a) as being unpatentable over Matsushita (JP 10062814 A – hereafter Matsushita) in view of Ogawa. Finally, claims 12, 13, 16, 25 and 26 stand rejected under 35 U.S.C. §103(a) as being unpatentable over Ishikawa in view of Matsushita and Ogawa. These rejections are respectfully traversed at least for the reasons provided below.

In the interest of expediting the allowance of this application, Applicant has amended independent claims 1-6, 10 and 11, as shown above, to further distinguish the presently claimed invention over the various combinations of Ishikawa, Ogawa, Koinuma and/or Matsushita.

Initially, Applicants contend that the verified English translation of the priority documents filed January 16, 2007, overcome the rejection of claims 1, 3, 4, 6, 7, 10-13, 16, 18, 19, 21 and 23-26 under 35 U.S.C. §102(e) as being anticipated by Yamazaki in that the priority documents show that the present invention described is not “by another.”

With respect to independent claims 1-6, 14 and 15, the Examiner asserts that the

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Docket No. 740756-2710
Application No. 10/771,277
Page 9

present invention is obvious over the combination of Ishikawa, Ogawa and Koinuma. Further, the Examiner asserts that Ishikawa shows in Figs. 6(d)-6(f) the feature of selectively forming a pattern 3 comprising a composition 3a which is emitted by used of droplet emitting means 222b (Fig. 8(b)). However, Applicants have amended independent claims 1, 3 and 4 to recite, *inter alia*, the feature of "baking the pattern (resist)." Support of this feature can be found at least on page 69, lines 6-19, FIG. 26(C) in the present specification. Ishikawa does not teach, disclose or suggest the feature of baking the pattern 3 though he discloses baking a resist film 3c in FIG. 6c. Further, Ogawa teaches a resist by using a liquid droplet ejection head at col. 31, lines 43-53, but does not teach, disclose or suggest baking the resist. Meanwhile, Koinuma is related to plasma processing, and therefore does not teach, disclose or suggest the feature of baking the resist. Thus, it cannot be said that the combination of Ishikawa with Ogawa and Koinuma makes the feature of baking the pattern obvious, as presently claimed.

With respect to independent claims 2, 5 and 6, Applicants have amended claims 2, 5 and 6 to commonly recite, *inter alia*, the features of "selectively forming a wiring;" "selectively forming a resist by use of droplet emitting means ... over the wiring;" "etching the wiring by use of plasma;" and "ashing the resist by use of plasma after etching the wiring." (See manufacturing process in Embodiment 1 and FIGS. 10A-11B of present application). However, Ishikawa discloses resist pattern 3 over a metal film 2a which is not selectively formed but entirely formed on a surface of substrate 1. Thus, Ishikawa fails to teach, disclose or suggest the manufacturing process features of selectively forming a wiring; selectively forming a resist by use of droplet emitting means, over the wiring; etching the wiring by use of plasma; and ashing the resist by use of plasma after etching the wiring, as presently claimed. Further, Ogawa and Koinuma do not teach, disclose or suggest the manufacturing process recited in claims 2, 5 and 6. Thus, it cannot be said that the combination of Ishikawa with Ogawa and Koinuma makes obvious the features of selectively forming a wiring; selectively forming a resist by use of droplet emitting means, over the wiring; etching the wiring by use of plasma; and ashing the resist by use of plasma after etching the wiring, as presently claimed.

With respect to independent claims 14 and 15, the arguments set forth above with respect to the obviousness rejection of claims 2, 5 and 6 over Ishikawa in view of Ogawa and

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Docket No. 740756-2710
Application No. 10/771,277
Page 10

Koinuma are also applicable to the obviousness rejection of independent claims 14 and 15 over Ishikawa in view of Ogawa and Koinuma.

Therefore, Applicants note that independent claims 1-6, 14 and 15 are allowable as discussed above. Any claim that depends from an allowable claim is allowable as well. Thus, Applicants respectfully request that the rejection to dependent claims 7, 17-21, 27 and 28 be removed.

With respect to independent claims 10 and 11, the Examiner asserts that Matsushita discloses pattern 10a is formed along the groove 12. However, Applicants have amended claims 10 and 11 to recite, *inter alia*, the features of "emitting a wiring material in the groove, by use of droplet emitting means to form a wiring in the groove," and "the droplet emitting head moves along the groove when emitting the wiring material." Matsushita disclose that the groove 12 is formed only along a line x. Further, if combined with Ogawa's droplet emitting head moves along the groove 12, the wiring is formed only at the line x, and as such the wiring would be rendered meaningless. In addition, Applicants contend that Ogawa and/or Matsushita do not teach or suggest the feature of the droplet emitting head moves along the groove when emitting the wiring material. Thus, it cannot be said that the combination of Matsushita with Ogawa makes obvious the features of emitting a wiring material in the groove, by use of droplet emitting means to form a wiring in the groove and the droplet emitting head moves along the groove when emitting the wiring material, as presently claimed.

Therefore, Applicants note that independent claims 10 and 11 are allowable as discussed above. Any claim that depends from an allowable claim is allowable as well. Thus, Applicant respectfully requests that the rejection to dependent claims 23 and 24 be removed.

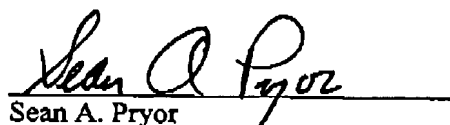
With respect to the rejection of claims 12, 13, 25 and 26, Applicants have canceled claims 12, 13, 25 and 26 thereby rendering this rejection moot.

10565806.1

Docket No. 740756-2710
Application No. 10/771,277
Page 11

In view of the foregoing, it is respectfully requested that the rejections of record be reconsidered and withdrawn by the Examiner, that claims 1-7, 10, 11, 14-21, 23, 24, 27 and 28 be allowed, and that the application be passed to issue. If a conference would expedite prosecution of the instant application, the Examiner is hereby invited to telephone the undersigned to arrange such a conference.

Respectfully submitted,



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